.062" PITCH COMPLIANT PIN

HD Stacker™

Solder-free, rugged board-to-board stackable connectors

PERFORMANCE SPECIFICATIONS

Current rating: 3 Amp

DWV: 638 VAC sea level

Insulation resistance:
5000 Megohms minimum @ 500 VDC

Contact resistance: 3 – 5 Milliohms

Operating temperature: -65°C to +200°C

Connector mating force (max):
(4 ounces) X (number of contacts)

Press-fit contact insertion force (max):
(22.5 pounds) X (number of contacts)

Durability: 500 mating cycles

Contact wipe: .050" minimum
(.150" @ max insertion)

MATERIALS AND FINISHES

Insulator: Polyphenylene sulfide (PPS); meets NASA outgassing requirements.

Contacts: Copper alloy, gold (50 to 100 microinches thick) over nickel (50 to 100 microinches thick) plating

Hardware: Copper alloy, nickel plated and/or 300 series stainless steel, passivated.

Encapsulant: Epoxy resin Hysol EE4215

PCB REQUIREMENTS

Board material: FR-4, Polyimide, or equivalent

Board thickness: .058" minimum

Drilled hole size: Ø.033" (#66 drill)

Plating material: Sn alloy or ENIG recommended

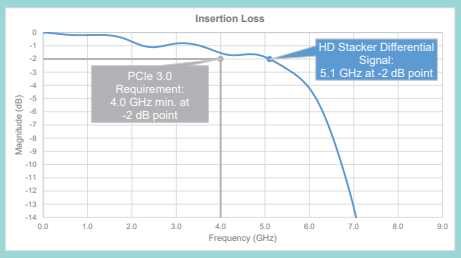
Total plating thickness: .001" – .002"

QUALIFICATION TESTING / HIGH-SPEED PERFORMANCE

HD Stacker connectors were qualified in accordance with MIL-DTL-55302G testing for:

- Contact engagement/ separation and retention
- DWV
- Electrical resistance
- Mechanical vibration/shock
- Insulation resistance
- Thermal shock
- Contact resistance
- Contact wipe - .150" min
- Humidity

High-frequency electrical performace tests were performed for: Insertion loss, return loss, crosstalk, and time domain performance metrics including impedance and eye pattern.



HD Stacker insertion loss compared to PCIe Rev. 3

Complete test reports are available at **www.glenair.com/test-reports-and-technical-information/index.htm#hd-stacker**

PCB LAYOUTS (COMPONENT SIDE)